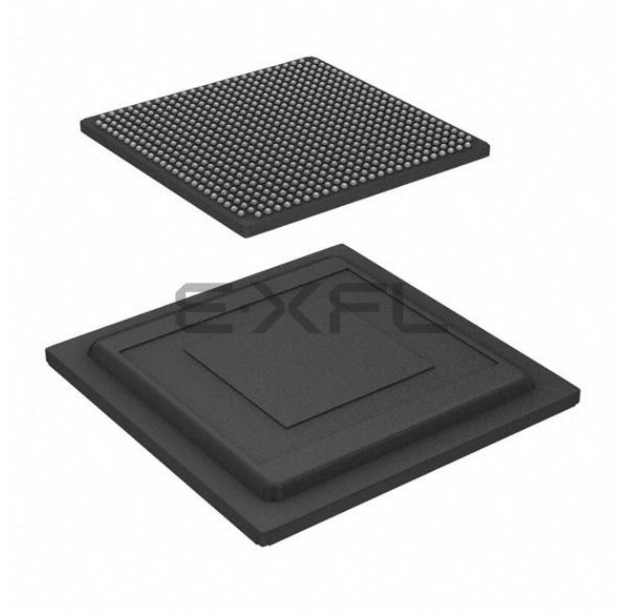

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	3537
Number of Logic Elements/Cells	75000
Total RAM Bits	8666112
Number of I/O	336
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	672-BBGA, FCBGA
Supplier Device Package	672-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5agxba1d4f27c5n

Symbol	Description	Condition	Minimum(1)	Typical	Maximum(1)	Unit
V_{CCIO}	I/O buffers power supply	3.3 V	3.135	3.3	3.465	V
		3.0 V	2.85	3.0	3.15	V
		2.5 V	2.375	2.5	2.625	V
		1.8 V	1.71	1.8	1.89	V
		1.5 V	1.425	1.5	1.575	V
		1.35 V	1.283	1.35	1.418	V
		1.25 V	1.19	1.25	1.31	V
		1.2 V	1.14	1.2	1.26	V
V_{CCD_FPLL}	PLL digital voltage regulator power supply	—	1.425	1.5	1.575	V
V_{CCA_FPLL}	PLL analog voltage regulator power supply	—	2.375	2.5	2.625	V
V_I	DC input voltage	—	–0.5	—	3.6	V
V_O	Output voltage	—	0	—	V_{CCIO}	V
T_J	Operating junction temperature	Commercial	0	—	85	°C
		Industrial	–40	—	100	°C
t_{RAMP}(4)	Power supply ramp time	Standard POR	200 µs	—	100 ms	—
		Fast POR	200 µs	—	4 ms	—

(1) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

(4) This is also applicable to HPS power supply. For HPS power supply, refer to t_{RAMP} specifications for standard POR when `HPS_PORSEL` = 0 and t_{RAMP} specifications for fast POR when `HPS_PORSEL` = 1.

Symbol	Description	Minimum[5]	Typical	Maximum[5]	Unit
V_{CCL_GXBL}	GX and SX speed grades—clock network power (left side)	1.08/1.12	1.1/1.15[6]	1.14/1.18	V
V_{CCL_GXBR}	GX and SX speed grades—clock network power (right side)				
V_{CCL_GXBL}	GT and ST speed grades—clock network power (left side)	1.17	1.20	1.23	V
V_{CCL_GXBR}	GT and ST speed grades—clock network power (right side)				

Related Information

Arria V GT, GX, ST, and SX Device Family Pin Connection Guidelines
Provides more information about the power supply connection for different data rates.

HPS Power Supply Operating Conditions

Table 1-5: HPS Power Supply Operating Conditions for Arria V SX and ST Devices

This table lists the steady-state voltage and current values expected from Arria V system-on-a-chip (SoC) devices with ARM®-based hard processor system (HPS). Power supply ramps must all be strictly monotonic, without plateaus. Refer to Recommended Operating Conditions for Arria V Devices table for the steady-state voltage values expected from the FPGA portion of the Arria V SoC devices.

Symbol	Description	Condition	Minimum[7]	Typical	Maximum[7]	Unit
V_{CC_HPS}	HPS core voltage and periphery circuitry power supply	–C4, –I5, –C5, –C6	1.07	1.1	1.13	V
		–I3	1.12	1.15	1.18	V

(5) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.
(7) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

I/O Standard	V_{CCIO} (V)			$V_{SWING(DC)}$ (V)		$V_{X(AC)}$ (V)			$V_{SWING(AC)}$ (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Max
SSTL-125	1.19	1.25	1.31	0.18	(15)	$V_{CCIO}/2 - 0.15$	$V_{CCIO}/2$	$V_{CCIO}/2 + 0.15$	$2(V_{IH(AC)} - V_{REF})$	$2(V_{IL(AC)} - V_{REF})$

Differential HSTL and HSUL I/O Standards

Table 1-18: Differential HSTL and HSUL I/O Standards for Arria V Devices

I/O Standard	V_{CCIO} (V)			$V_{DIF(DC)}$ (V)		$V_{X(AC)}$ (V)			$V_{CM(DC)}$ (V)			$V_{DIF(AC)}$ (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Typ	Max	Min	Max
HSTL-18 Class I, II	1.71	1.8	1.89	0.2	—	0.78	—	1.12	0.78	—	1.12	0.4	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.2	—	0.68	—	0.9	0.68	—	0.9	0.4	—
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	$V_{CCIO} + 0.3$	—	$0.5 \times V_{CCIO}$	—	$0.4 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.6 \times V_{CCIO}$	0.3	$V_{CCIO} + 0.48$
HSUL-12	1.14	1.2	1.3	0.26	0.26	$0.5 \times V_{CCIO} - 0.12$	$0.5 \times V_{CCIO}$	$0.5 \times V_{CCIO} + 0.12$	$0.4 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.6 \times V_{CCIO}$	0.44	0.44

Differential I/O Standard Specifications

Table 1-19: Differential I/O Standard Specifications for Arria V Devices

Differential inputs are powered by V_{CCPD} which requires 2.5 V.

Protocol	Sub-protocol	Data Rate (Mbps)
Common Public Radio Interface (CPRI)	CPRI E6LV	614.4
	CPRI E6HV	614.4
	CPRI E6LVII	614.4
	CPRI E12LV	1,228.8
	CPRI E12HV	1,228.8
	CPRI E12LVII	1,228.8
	CPRI E24LV	2,457.6
	CPRI E24LVII	2,457.6
	CPRI E30LV	3,072
	CPRI E30LVII	3,072
	CPRI E48LVII	4,915.2
	CPRI E60LVII	6,144
	CPRI E96LVIII(60)	9,830.4
Gbps Ethernet (GbE)	GbE 1250	1,250
OBSAI	OBSAI 768	768
	OBSAI 1536	1,536
	OBSAI 3072	3,072
	OBSAI 6144	6,144
Serial digital interface (SDI)	SDI 270 SD	270
	SDI 1485 HD	1,485
	SDI 2970 3G	2,970

(60) You can achieve compliance with TX channel restriction of one HSSI channel per six-channel transceiver bank.

Symbol	Parameter	Condition	Min	Typ	Max	Unit
t_{OUTPJ_DC}[67]	Period jitter for dedicated clock output in integer PLL	$F_{OUT} \geq 100$ MHz	—	—	175	ps (p-p)
		$F_{OUT} < 100$ MHz	—	—	17.5	mUI (p-p)
t_{FOUTPJ_DC}[67]	Period jitter for dedicated clock output in fractional PLL	$F_{OUT} \geq 100$ MHz	—	—	250[68], 175[69]	ps (p-p)
		$F_{OUT} < 100$ MHz	—	—	25[68], 17.5[69]	mUI (p-p)
t_{OUTCCJ_DC}[67]	Cycle-to-cycle jitter for dedicated clock output in integer PLL	$F_{OUT} \geq 100$ MHz	—	—	175	ps (p-p)
		$F_{OUT} < 100$ MHz	—	—	17.5	mUI (p-p)
$t_{FOUTCCJ\_DC}$[67]	Cycle-to-cycle jitter for dedicated clock output in fractional PLL	$F_{OUT} \geq 100$ MHz	—	—	250[68], 175[69]	ps (p-p)
		$F_{OUT} < 100$ MHz	—	—	25[68], 17.5[69]	mUI (p-p)
t_{OUTPJ_IO}[67][70]	Period jitter for clock output on a regular I/O in integer PLL	$F_{OUT} \geq 100$ MHz	—	—	600	ps (p-p)
		$F_{OUT} < 100$ MHz	—	—	60	mUI (p-p)
t_{FOUTPJ_IO}[67][68][70]	Period jitter for clock output on a regular I/O in fractional PLL	$F_{OUT} \geq 100$ MHz	—	—	600	ps (p-p)
		$F_{OUT} < 100$ MHz	—	—	60	mUI (p-p)
t_{OUTCCJ_IO}[67][70]	Cycle-to-cycle jitter for clock output on a regular I/O in integer PLL	$F_{OUT} \geq 100$ MHz	—	—	600	ps (p-p)
		$F_{OUT} < 100$ MHz	—	—	60	mUI (p-p)
$t_{FOUTCCJ\_IO}$[67][68][70]	Cycle-to-cycle jitter for clock output on a regular I/O in fractional PLL	$F_{OUT} \geq 100$ MHz	—	—	600	ps (p-p)
		$F_{OUT} < 100$ MHz	—	—	60	mUI (p-p)

(67) Peak-to-peak jitter with a probability level of 10^{-12} (14 sigma, 99.99999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLL, when an input jitter of 30 ps is applied. The external memory interface clock output jitter specifications use a different measurement method and are available in Memory Output Clock Jitter Specification for Arria V Devices table.

(68) This specification only covered fractional PLL for low bandwidth. The f_{VCO} for fractional value range 0.05–0.95 must be ≥ 1000 MHz.

(69) This specification only covered fractional PLL for low bandwidth. The f_{VCO} for fractional value range 0.20–0.80 must be ≥ 1200 MHz.

(70) External memory interface clock output jitter specifications use a different measurement method, which are available in Memory Output Clock Jitter Specification for Arria V Devices table.

Symbol	Condition	–I3, –C4			–I5, –C5			–C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$t_{x\ Jitter}$ -Emulated Differential I/O Standards with Three External Output Resistor Network	Total Jitter for Data Rate 600 Mbps – 1.25 Gbps	—	—	260	—	—	300	—	—	350	ps
	Total Jitter for Data Rate < 600 Mbps	—	—	0.16	—	—	0.18	—	—	0.21	UI
$t_{x\ Jitter}$ -Emulated Differential I/O Standards with One External Output Resistor Network	—	—	—	0.15	—	—	0.15	—	—	0.15	UI
t_{DUTY}	TX output clock duty cycle for both True and Emulated Differential I/O Standards	45	50	55	45	50	55	45	50	55	%
t_{RISE} and t_{FALL}	True Differential I/O Standards[82]	—	—	160	—	—	180	—	—	200	ps
	Emulated Differential I/O Standards with Three External Output Resistor Network	—	—	250	—	—	250	—	—	300	ps
	Emulated Differential I/O Standards with One External Output Resistor Network	—	—	500	—	—	500	—	—	500	ps

(82) This applies to default pre-emphasis and V_{OD} settings only.

DPA Lock Time Specifications

Figure 1-4: Dynamic Phase Alignment (DPA) Lock Time Specifications with DPA PLL Calibration Enabled

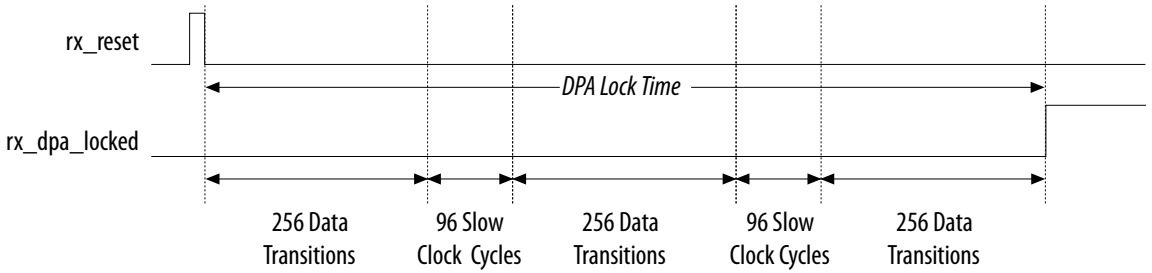


Table 1-41: DPA Lock Time Specifications for Arria V Devices

The specifications are applicable to both commercial and industrial grades. The DPA lock time is for one channel. One data transition is defined as a 0-to-1 or 1-to-0 transition.

Standard	Training Pattern	Number of Data Transitions in One Repetition of the Training Pattern	Number of Repetitions per 256 Data Transitions(84)	Maximum Data Transition
SPI-4	00000000001111111111	2	128	640
Parallel Rapid I/O	00001111	2	128	640
	10010000	4	64	640
Miscellaneous	10101010	8	32	640
	01010101	8	32	640

(84) This is the number of repetitions for the stated training pattern to achieve the 256 data transitions.

HPS PLL Input Jitter

Use the following equation to determine the maximum input jitter (peak-to-peak) the HPS PLLs can tolerate. The divide value (N) is the value programmed into the denominator field of the VCO register for each PLL. The PLL input reference clock is divided by this value. The range of the denominator is 1 to 64.

Maximum input jitter = Input clock period × Divide value (N) × 0.02

Table 1-50: Examples of Maximum Input Jitter

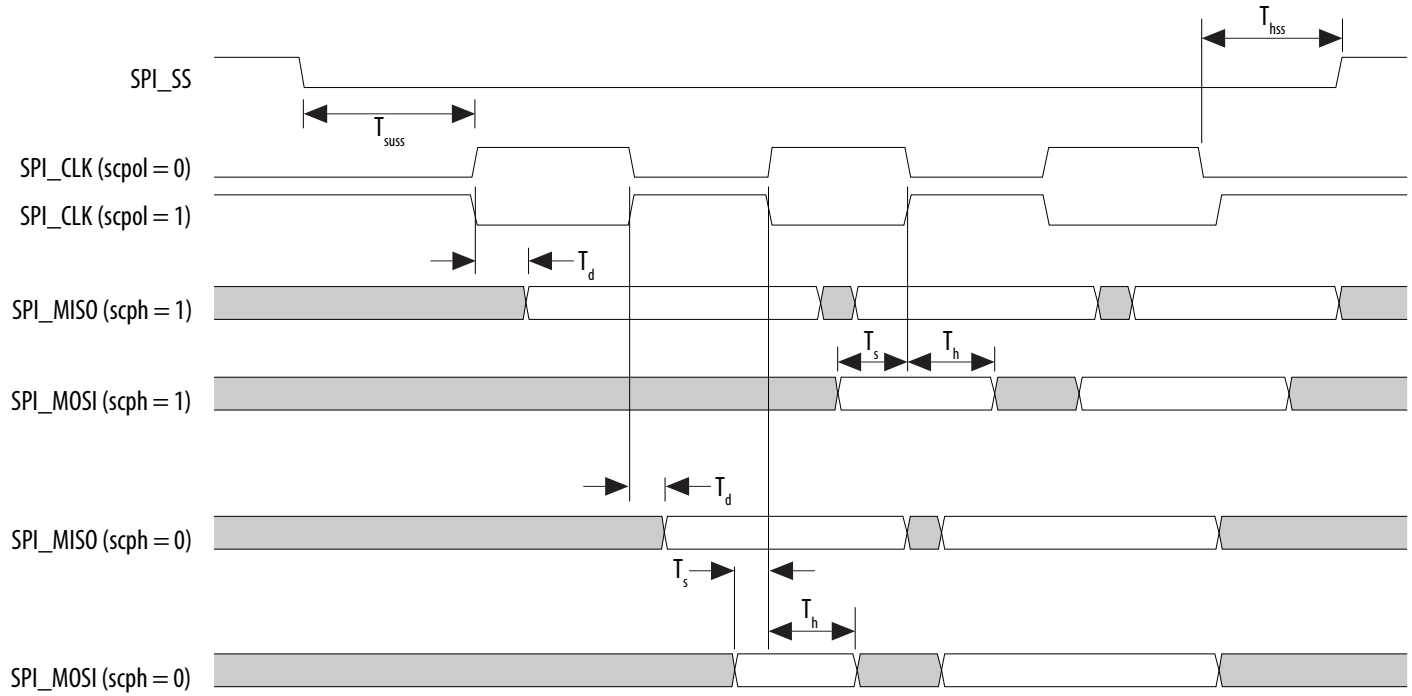
Input Reference Clock Period	Divide Value (N)	Maximum Jitter	Unit
40 ns	1	0.8	ns
40 ns	2	1.6	ns
40 ns	4	3.2	ns

Quad SPI Flash Timing Characteristics

Table 1-51: Quad Serial Peripheral Interface (SPI) Flash Timing Requirements for Arria V Devices

Symbol	Description	Min	Typ	Max	Unit
F_{clk}	SCLK_OUT clock frequency (External clock)	—	—	108	MHz
T_{qspi_clk}	QSPI_CLK clock period (Internal reference clock)	2.32	—	—	ns
$T_{dutycycle}$	SCLK_OUT duty cycle	45	—	55	%
$T_{dssfrst}$	Output delay QSPI_SS valid before first clock edge	—	1/2 cycle of SCLK_OUT	—	ns
T_{dsslst}	Output delay QSPI_SS valid after last clock edge	–1	—	1	ns
T_{dio}	I/O data output delay	–1	—	1	ns
T_{din_start}	Input data valid start	—	—	$(2 + R_{delay}) \times T_{qspi\_clk} - 7.52$ (85)	ns

Figure 1-10: SPI Slave Timing Diagram



Related Information

SPI Controller, Arria V Hard Processor System Technical Reference Manual
Provides more information about rx_sample_delay.

SD/MMC Timing Characteristics

Table 1-54: Secure Digital (SD)/MultiMediaCard (MMC) Timing Requirements for Arria V Devices

After power up or cold reset, the Boot ROM uses `drvsel` = 3 and `smplsel` = 0 to execute the code. At the same time, the SD/MMC controller enters the Identification Phase followed by the Data Phase. During this time, the value of interface output clock `SDMMC_CLK_OUT` changes from a maximum of 400 kHz (Identification Phase) up to a maximum of 12.5 MHz (Data Phase), depending on the internal reference clock `SDMMC_CLK` and the `CSEL` setting. The value of `SDMMC_CLK` is based on the external oscillator frequency and has a maximum value of 50 MHz.

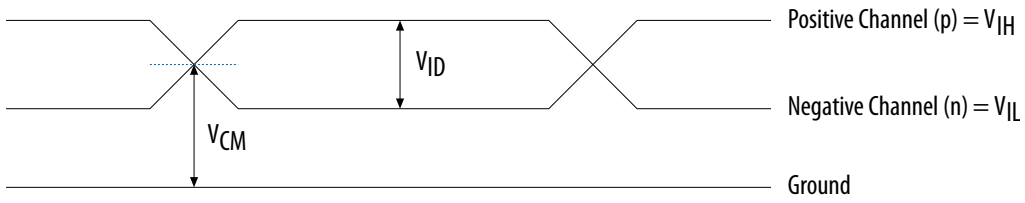
Symbol	Parameter	Typical	Unit
D_{OUTBUF}	Rising and/or falling edge delay	0 (default)	ps
		50	ps
		100	ps
		150	ps

Glossary

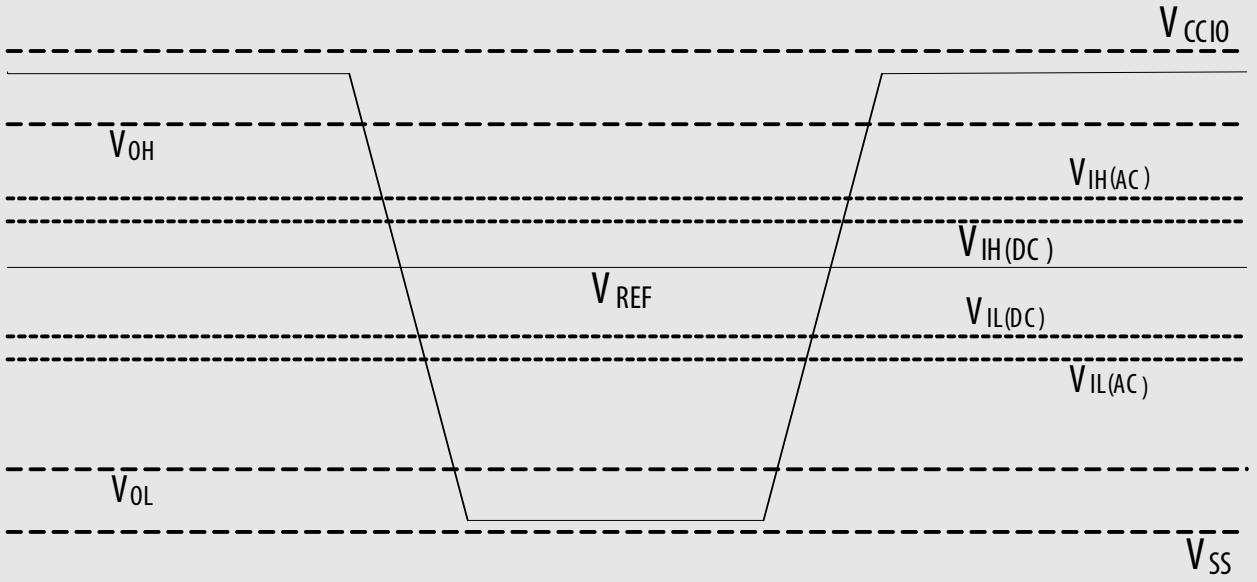
Table 1-78: Glossary

Term	Definition
Differential I/O standards	Receiver Input Waveforms

Single-Ended Waveform



Differential Waveform

Term	Definition
Single-ended voltage referenced I/O standard	The JEDEC standard for the SSTL and HSTL I/O defines both the AC and DC input signal values. The AC values indicate the voltage levels at which the receiver must meet its timing specifications. The DC values indicate the voltage levels at which the final logic state of the receiver is unambiguously defined. After the receiver input has crossed the AC value, the receiver changes to the new logic state. The new logic state is then maintained as long as the input stays beyond the DC threshold. This approach is intended to provide predictable receiver timing in the presence of input waveform ringing. Single-Ended Voltage Referenced I/O Standard 
t_C	High-speed receiver/transmitter input and output clock period.
TCCS (channel-to-channel-skew)	The timing difference between the fastest and slowest output edges, including the t_{CO} variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the Timing Diagram figure under SW in this table).
t_{DUTY}	High-speed I/O block—Duty cycle on high-speed transmitter output clock.

Term	Definition
t_{FALL}	Signal high-to-low transition time (80–20%)
t_{INCCJ}	Cycle-to-cycle jitter tolerance on the PLL clock input
t_{OUTPJ_IO}	Period jitter on the GPIO driven by a PLL
t_{OUTPJ_DC}	Period jitter on the dedicated clock output driven by a PLL
t_{RISE}	Signal low-to-high transition time (20–80%)
Timing Unit Interval (TUI)	The timing budget allowed for skew, propagation delays, and the data sampling window. (TUI = 1/ (Receiver Input Clock Frequency Multiplication Factor) = t_C/w)
$V_{CM(DC)}$	DC common mode input voltage.
V_{ICM}	Input common mode voltage—The common mode of the differential signal at the receiver.
V_{ID}	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
$V_{DIF(AC)}$	AC differential input voltage—Minimum AC input differential voltage required for switching.
$V_{DIF(DC)}$	DC differential input voltage— Minimum DC input differential voltage required for switching.
V_{IH}	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.
$V_{IH(AC)}$	High-level AC input voltage
$V_{IH(DC)}$	High-level DC input voltage
V_{IL}	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.
$V_{IL(AC)}$	Low-level AC input voltage
$V_{IL(DC)}$	Low-level DC input voltage
V_{OCM}	Output common mode voltage—The common mode of the differential signal at the transmitter.
V_{OD}	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission line at the transmitter.
V_{SWING}	Differential input voltage
V_X	Input differential cross point voltage

Date	Version	Changes
August 2013	3.5	• Removed "Pending silicon characterization" note in Table 29. • Updated Table 25.
August 2013	3.4	• Removed Preliminary tags for Table 1, Table 2, Table 3, Table 4, Table 5, Table 6, Table 7, Table 9, Table 12, Table 13, Table 14, Table 15, Table 16, Table 17, Table 18, Table 19, Table 20, Table 21, Table 22, Table 23, Table 24, Table 25, Table 26, Table 27, Table 28, Table 29, Table 30, Table 31, Table 35, Table 36, Table 51, Table 53, Table 54, Table 55, Table 56, Table 57, Table 60, Table 62, and Table 64. • Updated Table 1, Table 3, Table 11, Table 19, Table 20, Table 21, Table 22, Table 25, and Table 29.
June 2013	3.3	Updated Table 20, Table 21, Table 25, and Table 38.
May 2013	3.2	• Added Table 37. • Updated Figure 8, Figure 9, Figure 20, Figure 22, and Figure 23. • Updated Table 1, Table 5, Table 10, Table 13, Table 19, Table 20, Table 21, Table 23, Table 29, Table 39, Table 40, Table 46, Table 56, Table 57, Table 60, and Table 64. • Updated industrial junction temperature range for –I3 speed grade in "PLL Specifications" section.
March 2013	3.1	• Added HPS reset information in the "HPS Specifications" section. • Added Table 60. • Updated Table 1, Table 3, Table 17, Table 20, Table 29, and Table 59. • Updated Figure 21.

Date	Version	Changes

November 2012	3.0	• Updated Table 2, Table 4, Table 9, Table 14, Table 16, Table 17, Table 20, Table 21, Table 25, Table 29, Table 36, Table 56, Table 57, and Table 60.
		• Removed table: Transceiver Block Jitter Specifications for Arria V Devices.
		• Added HPS information:
		  • Added "HPS Specifications" section.
		  • Added Table 38, Table 39, Table 40, Table 41, Table 42, Table 43, Table 44, Table 45, Table 46, Table 47, Table 48, Table 49, and Table 50.
		  • Added Figure 7, Figure 8, Figure 9, Figure 10, Figure 11, Figure 12, Figure 13, Figure 14, Figure 15, Figure 16, Figure 17, Figure 18, and Figure 19.
		  • Updated Table 3 and Table 5.

October 2012	2.4	• Updated Arria V GX $V_{CCR\_GXBL/R}$, $V_{CCT\_GXBL/R}$, and $V_{CCL\_GXBL/R}$ minimum and maximum values, and data rate in Table 4. • Added receiver V_{ICM} (AC coupled) and V_{ICM} (DC coupled) values, and transmitter V_{OCM} (AC coupled) and V_{OCM} (DC coupled) values in Table 20 and Table 21.
August 2012	2.3	Updated the SERDES factor condition in Table 30.
July 2012	2.2	• Updated the maximum voltage for V_I (DC input voltage) in Table 1. • Updated Table 20 to include the Arria V GX -I3 speed grade. • Updated the minimum value of the fixedclk clock frequency in Table 20 and Table 21. • Updated the SERDES factor condition in Table 30. • Updated Table 50 to include the IOE programmable delay settings for the Arria V GX -I3 speed grade.
June 2012	2.1	Updated $V_{CCR\_GXBL/R}$, $V_{CCT\_GXBL/R}$, and $V_{CCL\_GXBL/R}$ values in Table 4.

Lower number refers to faster speed grade.

L = Low power devices.

Transceiver Speed Grade	Core Speed Grade			
	C3	C4	I3L	I4
2	Yes	—	Yes	—
3	—	Yes	—	Yes

Absolute Maximum Ratings

Absolute maximum ratings define the maximum operating conditions for Arria V GZ devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms. The functional operation of the device is not implied for these conditions.

Caution: Conditions other than those listed in the following table may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

Table 2-2: Absolute Maximum Ratings for Arria V GZ Devices

Symbol	Description	Minimum	Maximum	Unit
V_{CC}	Power supply for core voltage and periphery circuitry	–0.5	1.35	V
V_{CCPT}	Power supply for programmable power technology	–0.5	1.8	V
V_{CCPGM}	Power supply for configuration pins	–0.5	3.9	V
V_{CC_AUX}	Auxiliary supply for the programmable power technology	–0.5	3.4	V
V_{CCBAT}	Battery back-up power supply for design security volatile key register	–0.5	3.9	V
V_{CCPD}	I/O pre-driver power supply	–0.5	3.9	V
V_{CCIO}	I/O power supply	–0.5	3.9	V
V_{CCD_FPLL}	PLL digital power supply	–0.5	1.8	V
V_{CCA_FPLL}	PLL analog power supply	–0.5	3.4	V

Hot Socketing

Table 2-14: Hot Socketing Specifications for Arria V GZ Devices

Symbol	Description	Maximum
$I_{IOPIN\ (DC)}$	DC current per I/O pin	300 µA
$I_{IOPIN\ (AC)}$	AC current per I/O pin	8 mA (124)
$I_{XCVR\text{-}TX\ (DC)}$	DC current per transceiver transmitter pin	100 mA
$I_{XCVR\text{-}RX\ (DC)}$	DC current per transceiver receiver pin	50 mA

Internal Weak Pull-Up Resistor

Table 2-15: Internal Weak Pull-Up Resistor for Arria V GZ Devices

All I/O pins have an option to enable the weak pull-up resistor except the configuration, test, and JTAG pins. The internal weak pull-down feature is only available for the JTAG TCK pin. The typical value for this internal weak pull-down resistor is approximately 25 kΩ .

Symbol	Description	V_{CCIO} Conditions (V) (125)	Value (126)	Unit
R_{PU}	Value of the I/O pin pull-up resistor before and during configuration, as well as user mode if you enable the programmable pull-up resistor option.	3.0 ±5%	25	k Ω
		2.5 ±5%	25	k Ω
		1.8 ±5%	25	k Ω
		1.5 ±5%	25	kΩ
		1.35 ±5%	25	k Ω
		1.25 ±5%	25	k Ω
		1.2 ±5%	25	k Ω

(124) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, $|I_{IOPIN}| = C\ dv/dt$, in which C is the I/O pin capacitance and dv/dt is the slew rate.
(125) The pin pull-up resistance values may be lower if an external source drives the pin higher than V_{CCIO}.
(126) These specifications are valid with a ±10% tolerance to cover changes over PVT.

Symbol/Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Programmable DC gain	DC gain setting = 0	—	0	—	—	0	—	dB
	DC gain setting = 1	—	2	—	—	2	—	dB
	DC gain setting = 2	—	4	—	—	4	—	dB
	DC gain setting = 3	—	6	—	—	6	—	dB
	DC gain setting = 4	—	8	—	—	8	—	dB

Related Information

Arria V Device Overview
For more information about device ordering codes.

Transmitter

Table 2-25: Transmitter Specifications for Arria V GZ Devices

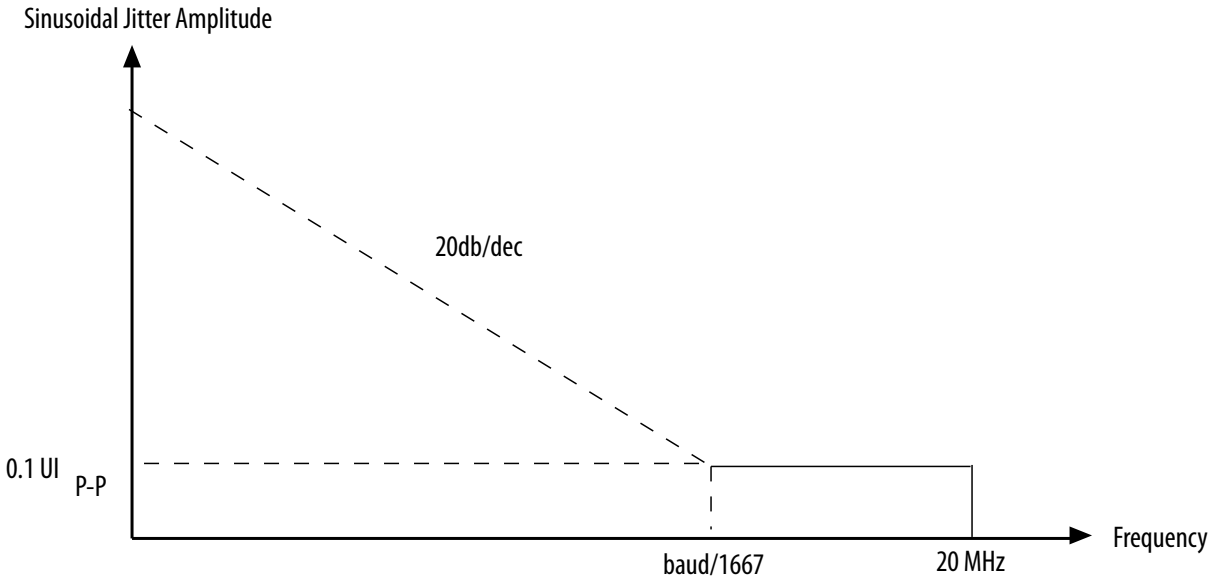
Speed grades shown refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Arria V Device Overview*.

Symbol/Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Supported I/O Standards	1.4-V and 1.5-V PCML							
Data rate (Standard PCS)	—	600	—	9900	600	—	8800	Mbps
Data rate (10G PCS)	—	600	—	12500	600	—	10312.5	Mbps

Symbol	Conditions	C3, I3L			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
True Differential I/O Standards - $f_{HSDRDPA}$ (data rate)	SERDES factor J = 3 to 10 (192), (193), (194), (195), (196), (197)	150	—	1250	150	—	1050	Mbps
	SERDES factor J ≥ 4 LVDS RX with DPA (193), (195), (196), (197)	150	—	1600	150	—	1250	Mbps
	SERDES factor J = 2, uses DDR Registers	(198)	—	(199)	(198)	—	(199)	Mbps
	SERDES factor J = 1, uses SDR Register	(198)	—	(199)	(198)	—	(199)	Mbps
f_{HSDR} (data rate)	SERDES factor J = 3 to 10	(198)	—	(200)	(198)	—	(200)	Mbps
	SERDES factor J = 2, uses DDR Registers	(198)	—	(199)	(198)	—	(199)	Mbps
	SERDES factor J = 1, uses SDR Register	(198)	—	(199)	(198)	—	(199)	Mbps

(192) The F_{MAX} specification is based on the fast clock used for serial data. The interface F_{MAX} is also dependent on the parallel clock domain which is design dependent and requires timing analysis.
(193) Arria V GZ RX LVDS will need DPA. For Arria V GZ TX LVDS, the receiver side component must have DPA.
(194) Arria V GZ LVDS serialization and de-serialization factor needs to be x4 and above.
(195) Requires package skew compensation with PCB trace length.
(196) Do not mix single-ended I/O buffer within LVDS I/O bank.
(197) Chip-to-chip communication only with a maximum load of 5 pF.
(198) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.
(199) The maximum ideal data rate is the SERDES factor (J) x the PLL maximum output frequency (fOUT) provided you can close the design timing and the signal integrity simulation is clean.
(200) You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.

Figure 2-5: LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate < 1.25 Gbps



Non DPA Mode High-Speed I/O Specifications

Table 2-46: High-Speed I/O Specifications for Arria V GZ Devices

When J = 3 to 10, use the serializer/deserializer (SERDES) block.

When J = 1 or 2, bypass the SERDES block.

Symbol	Conditions	C3, I3L			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Sampling Window	—	—	—	300	—	—	300	ps

Term	Definition
V_{OCM}	Output common mode voltage—The common mode of the differential signal at the transmitter.
V_{OD}	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.
V_{SWING}	Differential input voltage
V_X	Input differential cross point voltage
V_{OX}	Output differential cross point voltage
W	High-speed I/O block—clock boost factor

Document Revision History

Date	Version	Changes
February 2017	2017.02.10	• Changed the minimum value for t_{CD2UMC} in the “FPP Timing Parameters for Arria V GZ Devices When the DCLK-to-DATA[] Ratio is 1” table. • Changed the minimum value for t_{CD2UMC} in the "FPP Timing Parameters for Arria V GZ Devices When the DCLK-to-DATA[] Ratio is >1" table. • Changed the minimum value for t_{CD2UMC} in the "AS Timing Parameters for AS x1 and AS x4 Configurations in Arria V GZ Devices" table. • Changed the minimum value for t_{CD2UMC} in the "PS Timing Parameters for Arria V GZ Devices" table. • Changed the minimum number of clock cycles value in the "Initialization Clock Source Option and the Maximum Frequency for Arria V GZ Devices" table.